	Search Text	DBs
1	flip near5 chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
2	S11 and (attach$3 same chip same device)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
3	S12 and (inject$3 same mold$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
4	S13 and (hole or aperture or via or opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
5	S13 and ((hole or aperture or via or opening) same mold$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
6	S13 and ((hole or aperture or via or opening) same mold$3) and encapsulat$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
7	(264/272.11,272.17,328.1).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
8	S18 and ((inject$3 same mold$3) same encapsulat$3) and pin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
9	(264/272.17).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
10	S11 and (direct near5 chip near5 attach$3 same device)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
11	S18 and (direct near5 chip near5 attach$3 same device)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
12	(264/271.1,272.11,272.17,273,279.1).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
13	(438/112,124,127).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
14	(438/108,118,122,123).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
15	S29 and S33	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
16	S35 and ((hole or opening) same bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Search Text	DBs
17	(264/271.1,272.11,272.17,273,279.1).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
18	(438/112,124,127).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
19	S38 and S39	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
20	S40 and MOSFET	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
21	(264/272.17).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
22	S45 and (flip same bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
23	((264/272.17) or (438/127)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
24	S48 and MOSFET	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
25	S48 and (flag and MOSFET and (frame or support))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
26	S48 and encapsulat$3 and bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
27	S48 and encapsulat$3 and bump and ((cut$3 or remov$3) same resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
28	S48 and encapsulat$3 and bump and ((cut$3 or remov$3) same resin) and flip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
29	S48 and (bump near5 gold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
30	S48 and mosfet and (bump near5 gold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
31	((264/271.1,272.11,272.17,273,279.1) or (438/112,124,127)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
32	S61 and mosfet and (bump near5 gold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Search Text	DBs
33	S61 and (bump near5 gold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
34	S61 and (bump near5 gold) and flag	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
35	injection same mold$3 same pin same (hole or opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
36	injection same mold$3 same pin same (hole or opening) same reduc$3 same flash	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
37	("20040178537").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
38	injection same mold$3 same pin same (opening) same reduc$3 same flash	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
39	injection same mold$3 same pin same (opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
40	injection same mold$3 same pin same inside same mold same (opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB